# 8th International Conference on Electronics Packaging Technology
# (ICEPT 2007)

**August 14th – 17th, 2007, Shanghai, China**

Since 1994, ICEPT has been held for seven times in Beijing, Shanghai and Shenzhen of China, respectively. Since 2005 ICEPT has been held once a year due to rapid development of electronics packaging. As the only international electronics packaging technology conference organized and supported by authoritative academic organizations and leading industries, each ICEPT has attracted hundreds of participants from colleges, research institutes, packaging testing manufacturers, packaging testing equipment factories, packaging materials factories including distinguished experts, scholars and enterprises. The conference highly focuses on semiconductor packaging design, semiconductor packaging manufacturing, semiconductor packaging testing, LED packaging, MEMS packaging, system packaging and assembly, etc. The conference, which is domestically the highest-level and the most large-scale event for electronics packaging and testing technology, has become an important communication platform for advanced packaging technology. The 8th ICEPT will be held from August 14th to August 17th of 2007 in Shanghai, which is the biggest base of microelectronics industry and financial hub. We sincerely invite your participation.

## 1. Conference Information

### Time

Training course: 1）Registration time for training course: In the afternoon of August 13th, 2007 (Monday)
2）Training course-attending time: August 14th, 2007 (Tuesday)
Conference: 1）Conference-attending registration: August 14th, 2007 (Tuesday)
2）Conference time: August 15th-17th, 2007 (Wednesday to Friday)

### Venue

Sofitel Jin Jiang Oriental Hotel, 889 South Yang Gao Road, Pudong New Area, Shanghai, China

### Conference Website

http://www.icept.org

### Conference Scale

400-500 participants

### Conference Content

- **Advanced Packaging & System Packaging:** BGA, CSP, flip chip, WLP, nano-packaging, Cu/low-K packaging, 3D packaging, SiP and other advanced packaging and integration technologies.
- **High Density Substrate & SMT:** HDI, PCB, high performance multi-layer substrate, embedded substrate, micro via, microjoin, stencil print, reflow, and other novel assembly technologies that improve substrate density and performance.
- **Packaging Design & Modeling:** novel designs for various packaging/assembly, modeling, simulation and characterization solutions for electrical, thermal, optical & mechanical properties, multi-function & multi-scale modeling, simulation, validation methods and software technologies.
- **Packaging Materials & Processes:** interconnection and encapsulation materials including bonding wires, solder balls, solder pastes, conductive pastes, underfillings, plastic packaging materials, adhesives, thin-films, dielectric materials, substrate materials, frame materials, green electronic materials and other novel materials that enhance the packaging properties and reduce the cost，and various packaging and assembly processes.
- **Advanced Manufacturing Technology:** photolithography, laser processing, novel packaging/assembly technologies, advanced methods/softwares for modeling and monitoring of process effectiveness and cost analysis, and related manufacturing equipments.
- **Emerging Technologies:** sensors, actuators, MEMS, NEMS and MOEMS, optoelectronics & LED packaging, LCD, solid state lighting, passive and RF devices, power & HV devices, nanodevices based on nanowire, nanotubes and polymers, etc.
- **Quality & Reliability:** Quality monitoring and evaluation for packaging/assembly, advanced methods/technologies/tools for rapid reliability data collection and analysis system, reliability modeling & prediction, reliability issues in emerging technologies, testing equipments for quality control and reliability.

### Conference Sections

Symposium**,** short course, academic communication, exhibition of new product & technology

### Who Should Attend

Attendees of this conference in the past have been engineers, research scientists, equipment and material vendors, representatives from various packaging companies of packaging technology for IC, MEMS, Optoelectronics, LEDs, LCD, Magnetic Head, Sensors and PCB packaging and assembly. Due to the booming growth of the electronic/optoelectronic and emerging MEMS packaging industry in mainland China (including more than 300 IC packaging companies and several hundred LED packaging companies), this conference will provide a perfect platform for the exchange of information, research and industry development, and recruitment of young engineers.

## 2. Submission of Your Papers

If you want to submit a paper to this conference, please first send an abstract (500-1000 words) to our e-mail box technical.chair@icept.org or icept2007@sjtu.edu.cn (before May 31, 2007). Reported works in the abstract should be original and have not been published in other media or journals. The abstract should contain a clear statement of the purpose of the experiment, experimental results (including data, charts and pictures), conclusions and important references. All of the abstracts should be written in English based on the electronic template we send to you. We only accept electronic submission, which should include a word file and a PDF file simultaneously. Please put your detailed address (electronic mailbox, postal address, telephone and fax numbers) in the submitted abstract. All of the papers accepted by the ICEPT 2007 will be published in an IEEE conference proceeding. Research articles will be accepted and published in "Journal of Shanghai Jiao Tong University (English Edition)", which is a source journal of Engineering Index (Ei). Corresponding author will be charged for publication in the above journal. In addition, IEEE-CPMT will publish a special section for selected papers based on a peer review process. For more information, please go to our website of http://www.icept.org

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| **Important Deadlines** | May 31, 2007 | Submission of abstract |
| | June 15, 2007 | Notification of acceptance |
| | July 15, 2007 | Submission of final paper |

## 3. Organization

### Directed by

Chinese Institute of Electronics
Science & Technology Department, Ministry of Education of the People's Republic of China
Shanghai Municipality, China
Department of High and New Technology Development & Industrialization, Ministry of Science and Technology of the People's Republic of China
Department of Electronics Information Products, Ministry of Information Industry of the People's Republic of China
China International Culture Exchange Center

### Sponsored by

China Electronics Packaging Society (CEPS), Chinese Institute of Electronics
Shanghai Jiao Tong University (SJTU), China
The IEEE Components, Packaging, and Manufacturing Technology Society (IEEE-CPMT)
International Microelectronics and Packaging Society (IMAPS)

### Organized by

Shanghai Jiao Tong University (SJTU), China
Beijing Faith Counseling Co., Ltd

### Co-sponsored by

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# ICEPT 2007 ABSTRACT SUBMISSION

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**Author's Names:** Please type in the names, affiliations, addresses, phone/fax numbers, & email addresses of all authors here

## Primary Contact:

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Address: Complete mailing address, Town, State ZIP, Country
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Please type in an abstract (500-1000 words) of your paper here. The abstract should clearly and concisely state the specific results (including data, drawings, graphs or photographs), why they are important, and how they relate to prior work. All submissions must be in English. The required file format is Microsoft Word and must follow the format provided.

Submit the abstract to technical.chair@icept.org or icept2007@sjtu.edu.cn by May 31, 2007.

2007

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## 8th International Conference on Electronics Packaging Technology

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